ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type * Distribute										
Supplier	· Information														
Company	Company name*			Company unique ID			Unique ID Authority				Respons	Response Date*			
onsemi												2024-05-18			
Contact Na	ame		Title - Contac	Title - Contact			Phone - Contact*				Email - 0	Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance			N.	NA				Product-Env-Stewards@onsemi.com				
Authorized	d Representative*		Title - Representative			Ph	Phone - Representative*				Email - Representative*				
Product-E	Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name			E	Effective Date	Version	Mai	Manufacturing Site		Weight*	UOM	Unit Type	
	NV24C0 BG		04MUW3VLT	MUW3VLT 4KB I2C SER EEPROM UDFN WETTABLE FLANKS (with HVET, for Vcc range)			024-05-18		TH	TH6		0.28	mg	Each	
Manufacturing Proccess Information															
	Terminal Plating / Grid Array	Ferminal Base Alloy J-STD-		J-STD-020 MSL Rati	ing	Peak Proces	ess Body Temperature Max Time at Peak		Temperature Number of		of Reflow Cycl	es			
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			Alloy			260	260 C 30		30	seconds 3				
Comments															
level 1 - maximum time at peak temperature during soldering is 10-30 seconds															
For more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appli											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.116	mg	Supplier	Silicon (Si)	7440-21-3		0.116	mg
Die Attach	0.055	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0033	mg
			Supplier	Silver (Ag)	7440-22-4		0.0448	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0033	mg
			Supplier	Misc.	Proprietary Data		0.0003	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0033	mg
Lead Frame	2.96	mg	Supplier	Tin (Sn)	7440-31-5		0.0074	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0065	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0074	mg
			Supplier	Copper (Cu)	7440-50-8		2.9387	mg
Mold Compound-Black	5.725	mg		Epoxy resin	proprietary data		0.2862	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1317	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2862	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0229	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8663	mg
Plating	0.057	mg	Supplier	Palladium (Pd)	7440-05-3		0.0035	mg
			В	Nickel (Ni)	7440-02-0		0.0528	mg
			Supplier	Gold (Au)	7440-57-5		0.0006	mg
Plating-Sn	0.307	mg	Supplier	Tin (Sn)	7440-31-5		0.307	mg
Wire Bond - Au	0.06	mg	Supplier	Gold (Au)	7440-57-5		0.06	mg